

# ACER\_BAP31

## MAIN BOARD

2008.12.29

Tuesday, March 10, 2009		X01
DATE	CHANGE NO.	REV.

	EE	DATE	POWER	DATE	<b>INVENTEC</b>			
DRAWER					TITLE <b>ACER JM31</b>			
DESIGN								
CHECK RESPONSIBLE								
SIZE=					VER:			
FILE NAME: XXXX-XXXX-XXXX					SIZE	CODE	DOC NUMBER	REV
PN	J3X3X3X3X3X3X				C	X01	D-CS-1310A2284501-JALG	X01
					SHEET 1 of 38			

# 1. Schematic Page Description :

## Montevina Schematic Ver : X01

- |                                  |                                 |
|----------------------------------|---------------------------------|
| 1. Title                         | 24. Clock Generator             |
| 2. Schematic Page DESCR          | 25. DDR3 SDRAM SO-DIMM0         |
| 3. Block Diagram                 | 26. DDR3 SDRAM SO-DIMM1         |
| 4. Annotations                   | 27. ICH9M CPU/IDE/SATA(1/4)     |
| 5. Schematic Modify              | 28. ICH9M PCI/PCIE/DMI/USB(2/4) |
| 6. Timing Diagram                | 29. ICH9M GPIO(3/4)             |
| 7. Power Block Diagram           | 30. ICH9M Power/GND(4/4)        |
| 8. Adaptor in/Charge             | 31. LCD CNN/SATA/3G/WLAN        |
| 9. 5VLA/5VA/3VA                  | 32. KBC ITE8512F                |
| 10. 3VS/5VS/1.5V (DDR3)          | 33. IO CN                       |
| 11. 1.05VS/1.5S/1.8V/1.5VA       |                                 |
| 12. Power Latch/1.5VS/SCREW HOLE |                                 |
| 13. CPU Core Power               |                                 |
| 14. GPU Core Power               |                                 |
| 15. Penryn Processor(1/2)        |                                 |
| 16. Penryn Processor(2/2)        |                                 |
| 17. CPU Thermal                  |                                 |
| 18. Cantiga Host(1/6)            |                                 |
| 19. Cantiga DMI/Graph(2/6)       |                                 |
| 20. Cantiga DDRII(3/6)           |                                 |
| 21. Cantiga Power(4/6)           |                                 |
| 22. Cantiga Power(5/6)           |                                 |
| 23. Cantiga Ground(6/6)          |                                 |

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TITLE			
BAP31 (Penryn+Cantiga+ICH9M)SFF			
Schematic Page			
SIZE	CODE	DOC NUMBER	REV
Custom	X01	D-CS-1310A284501-ALG	X01
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CHANGE by Milen Liu DATE Tuesday, March 10, 2009

### 3. Block Diagram :

**PLL**  
ICS9LPRS365BKLF  
TSSP 64P P.25

266MHz+/- x2 (CPU, NB)  
100MHz+/- x7  
48MHz x2 (ICH, SC)  
33MHz x6  
14MHz x2 (ICH, SIO)  
27MHz/96MHz+/-x1

**MiniCard #1**  
WLAN  
Port#1 P.43

**EASY Board**  
GbE  
RTL8111CP P.37

**Audio Board**  
HDA 24MHz  
MDC1-5 P.44  
RJ11 P.44  
IntMic Stereo P.39  
Analog In P.39  
Audio Codec ALC269X-GR P.38  
SPK P.39  
Analog Out P.39

**CR Board**  
USB8 REALTEK RTS5159

**GP/FP Board**  
Flash ROM P.45  
KB P.45  
Stick  
Glide Pad P.34

**Table:**

SIZE	CODE	DOC NUMBER	REV
Custom	X01	D-CS-1310A284501-ALG	X01

**INVENTEC**

**BAP31 (Penryn+Cantiga+ICH9M-SFF)**  
Block Diagram

CHANGE by: Miles Liu DATE: Tuesday, March 10, 2009 SHEET: 1 of 38

# 4. Net name Description :

## Voltage Rails

DCIN	Primary DC system power supply
+5VLA	5.0V always on power rail by LATCH or ACIN
+5VA	5.0V always on power rail by ECPWON
+3VA	3.3V always on power rail by ECPWON
+5VS	5.0V switched power rail by SLP_S3#_3R
+3VS	3.3V switched power rail by SLP_S3#_3R
+1.8VS	1.8V switched power rail by SLP_S3#_3R
VCC_CORE	Core Voltage for CPU
+1.05VS	1.05V power rail for AGTL+ termination/Core for GMCH by SLP_S3#_3R
+1.25VS	1.25V switched power rail by SLP_S3#_3R
+1.5VS	1.5V power rail for CPU PLL/DMI;PCIE;DDRIII DLLs for GMCH/Core;PCIE for ICH9m by SLP_S3#_3R
+1.5V	1.5V power rail for DDRII by SLP_S5#_3R
0.75VDDT_DDRIII	0.75V DDRII Termination Voltage by SLP_S3#_3R

## Part Naming Conventions

C	=	Capacitor
CN	=	Connector
D	=	Diode
F	=	Fuse
L	=	Inductor
Q	=	Transistor
R	=	Resistor
RP	=	Resistor Pack
U	=	Arbitrary Logic Device
Y	=	Crystal and Osc

## Net Name Suffix

#	=	Active Low signal
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# 5. Board Stack up Description

## PCB Layers

Layer 1		Component Side, Microstrip signal Layer
Layer 2		Ground Plane
Layer 3		Stripline Layer
Layer 4		Power Plane
Layer 5		Stripline Layer
Layer 6		Stripline Layer
Layer 7		Ground Plane
Layer 8		Solder Side, Microstrip signal Layer

	Differential Impedance for Microstrip	Differential Impedance for Stripline
Host Clock	95 ohm +/- 20%	95 ohm +/- 20%
PCI-E Clock	95 ohm +/- 20%	95 ohm +/- 20%
DDR3 CLK	75 ohm +/- 20%	75 ohm +/- 20%
DDR3 Strobe	90 ohm +/- 20%	90 ohm +/- 20%
DMI Bus	95 ohm +/- 20%	95 ohm +/- 20%
PCIE Bus	95 ohm +/- 20%	95 ohm +/- 20%
SDVO	95 ohm +/- 20%	95 ohm +/- 20%
SATA	95 ohm +/- 20%	95 ohm +/- 20%
USB	90 ohm +/- 20%	90 ohm +/- 20%
LVDS	95 ohm +/- 20%	95 ohm +/- 20%
Lan	95 ohm +/- 20%	95 ohm +/- 20%

Power Rail	Destination	Voltage	SO Current
VCC_CORE	Penryn SFF HFM: LFM:	1.3319V-1.4375V-1.4591V 0.9221V-0.9625V-0.9739V	18A
1.05VS	Penryn SFF : AGTL+ termination Cantiga GS: Core Cantiga GS: PCIE Cantiga GS:Core+IMEL+HSIO Cantiga GS:VCC_GMCH Cantiga GS:VCCA_SM_CK and NCTF Cantiga GS:VCC_DMI Cantiga GS:VCCA_SM Cantiga GS:VTT ICH9M:VCC1_05 ICH9M:DMI ICH9M:CPU_IO	1V-1.05V-1.10V 0.997V-1.05V-1.102V 0.9975V-1.05V-1.1025V 0.9975V-1.05V-1.1025V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V	4.5A 8.7A 1.78A 2.898A 10.154A 37.95mA 456mA 747.5mA 852mA 1.634A 48mA 2mA
1.5VS	Penryn SFF PLL Cantiga GS: QDAC Cantiga GS: LVDS Cantiga GS: TVDAC Cantiga GS: Various PLLS analog supply Cantiga GS: VCC_SM_CK Cantiga GS: VCC_SM ICH9M:PCIE_ICH ICH9M:SATA_ICH ICH9M:VCC_GLAN Mini Card: Express Card:	1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.71V-1.8V-1.89V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V	130mA 0.5mA 60.31mA 35mA 485mA 149.5mA 3.1625A 646mA 1.342A 80mA 650mA
1.5V	Cantiga GS: DDRIII System Memory	1.425V-1.5V-1.575V	3.1A(800M) 4.1A(1067M)
0.75VDDT_DDRIII	DDRIII Terminator:	0.7125V-0.75V-0.7875V	1.0A
3VS	Cantiga GS: HV CMOS Cantiga GS: VCCS_TV DAC ICH9M:VCC3_3 ICH9M:VCCGLAN3_3 Thermal Sensor: Mini Card: UMTS Express Card: CLK Generator: ICS9LPRS365BKLFT Mini Card: WirelessLan Bluetooth: Super I/O: IT8305E Azalia Codec: ALC262 Azalia MDC:	3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.0V-3.3V-3.6V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.0V-3.3V-3.6V 3.0V-3.3V-3.6V	105.3mA 78mA 308mA 1mA 5mA 1.3A 500mA
1.8VS	DVI	3.0V-3.3V-3.6V	120mA
3VA	ICH9M: RTC ICH9M:VCCSUS3_3 ICH9M:VCCCL3_3 ICH9M:VCCLAN3_3 LCD: Lan:AR8131 Azalia MDC: Flash ROM: BIOS	2V-3.3V-3.465V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.0V-3.3V-3.6V 3.0V-3.3V-3.6V 3.0V-3.3V-3.6V	6uA 212mA 73mA 78mA 2A 1A
5VS	Cardreader: RTS5159 Azalia Codec: ALC269 HDD: SATA ODD: SATA Audio AMP: G1432 Inverter: WebCam	3.0V-3.3V-3.6V 3.0V-3.3V-3.6V 4.75V-5.0V-5.25V 4.75V-5.0V-5.25V 4.75V-5.0V-5.25V	Max: 1.5A ; R/W: 460mA ; STDBY: 70mA Max: 1.5A ; R/W: 900mA ; STDBY: 45mA
5VA	USB: x 2 ports USB	4.75V-5.0V-5.25V 5VA 5VA	1A 2A 1.5A
5VLA	Control Power		
3VLA	EC: ITE8512E	3.0V-3.3V-3.6V	300mA

INVENTEC			
BAP31 (Penryn+Cantiga+ICH9M)SFF			
ANNOTATIONS			
SIZE	CODE	DOC NUMBER	REV
Custom	X01	D-CS-1310A284501-ALG	X01
SHEET 4 of 36			

# 6.Schematic modify Item and History :

2009.0108

- 1. ADD USB P3 for Docking, USB P5 for Finger printer,  
Modify CN5 -----P28
- 2. Modify CN20 to 50pin-----P33
- 3. Move PWR\_SWIN# from CN14 to CN20
- 4. ADD TPM module-----P34

2009.0109

- 1. ADD DOCK\_USB\_EN, DOCK\_CRT\_IN#-----P32,33

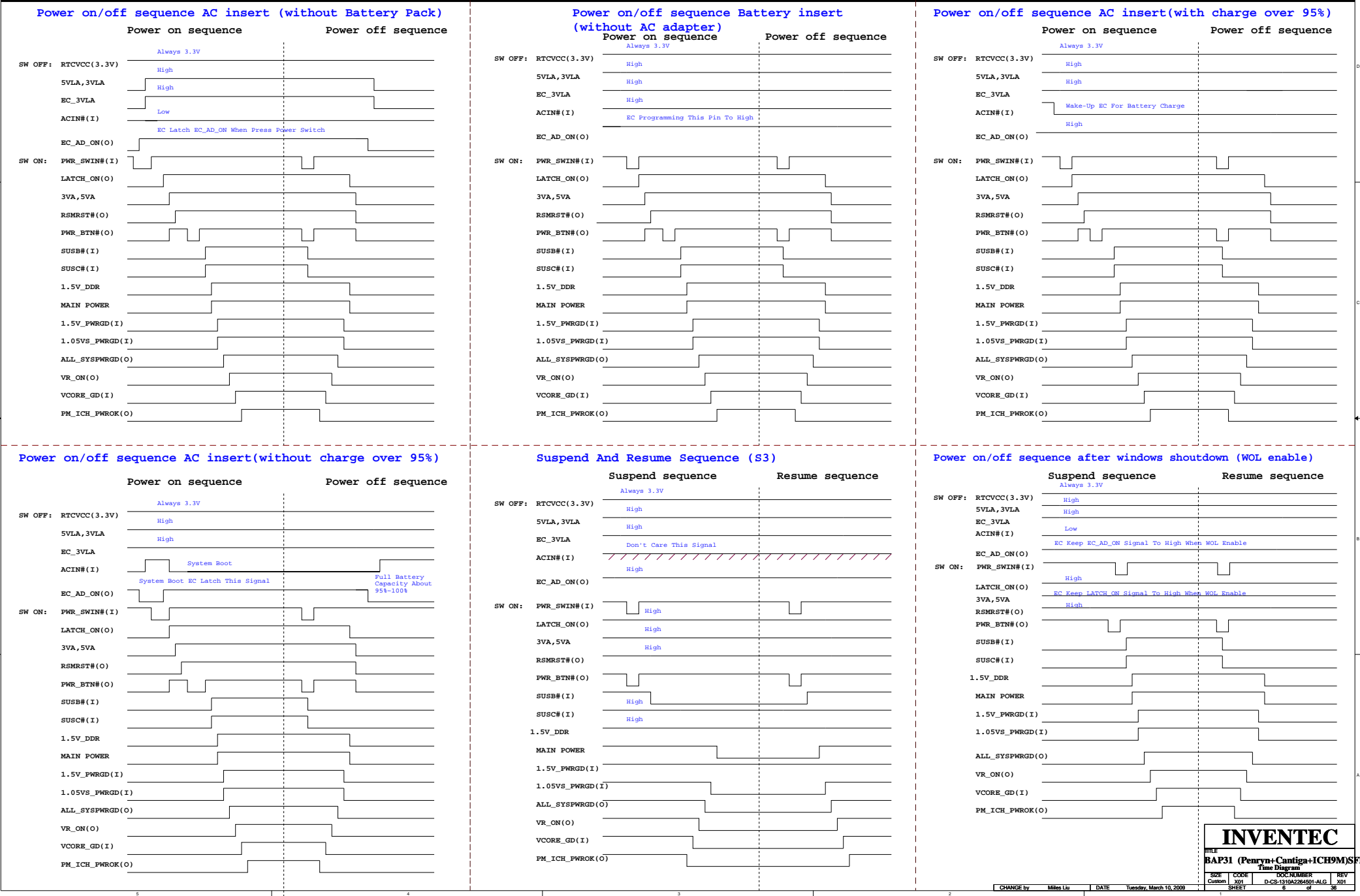
2009.0112

- 1. Change power item: R490,R291,BAT CNN TH PIN

INVENTEC			
TITLE BAP31 (Penryn+Contiga+ICH9M)SFF			
Schematic Modify			
SIZE Custom	CODE X01	DOC NUMBER D-CS-1310A284501-ALG	REV X01
CHANGE by Miles Liu		DATE Tuesday, March 10, 2009	
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# SYSTEM POWER ON/OFF SEQUENCE

Drawing : Wendy, Huang

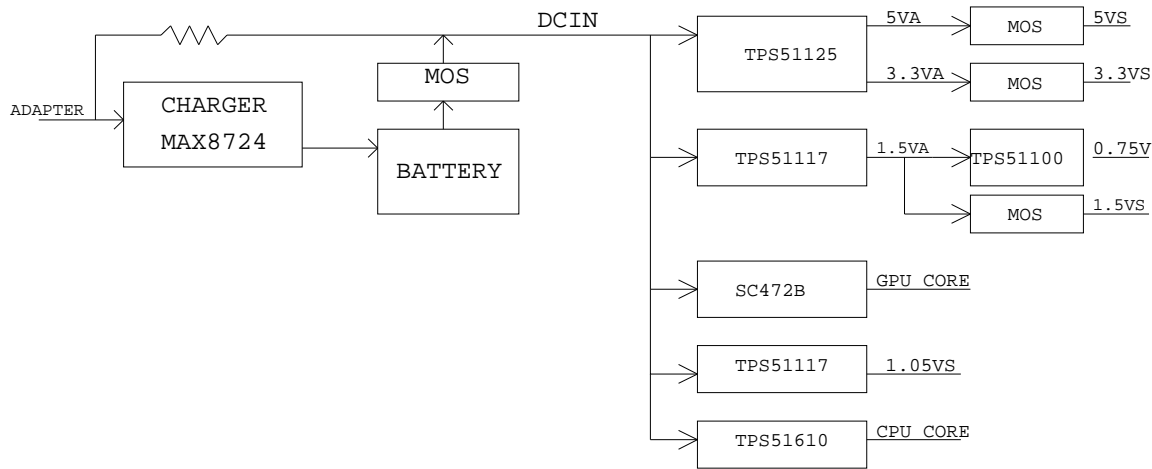


INVENTEC

FILE  
BAP31 (Penryn+Cantiga+ICH9M)SFF  
Time Diagram

SIZE CODE DOC NUMBER REV  
Custom XH D-55-1310A298600-ALG XH1  
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# Power Block Diagram :

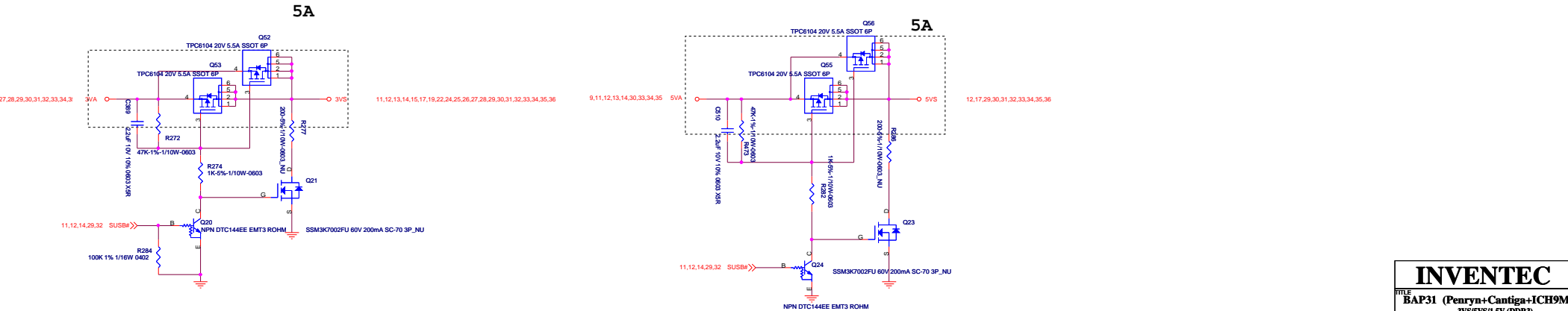
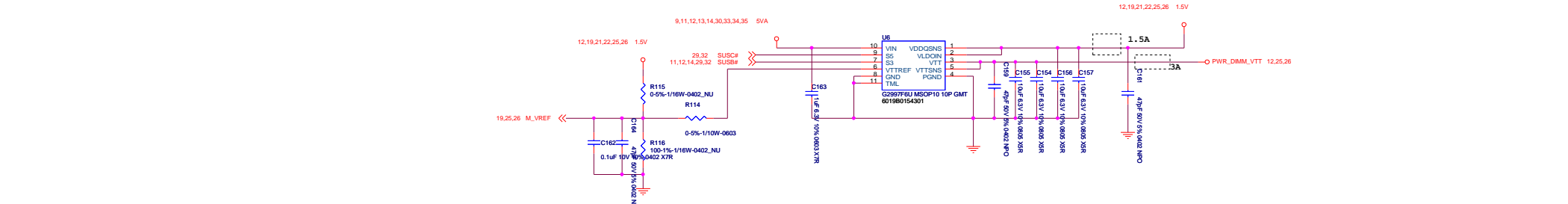
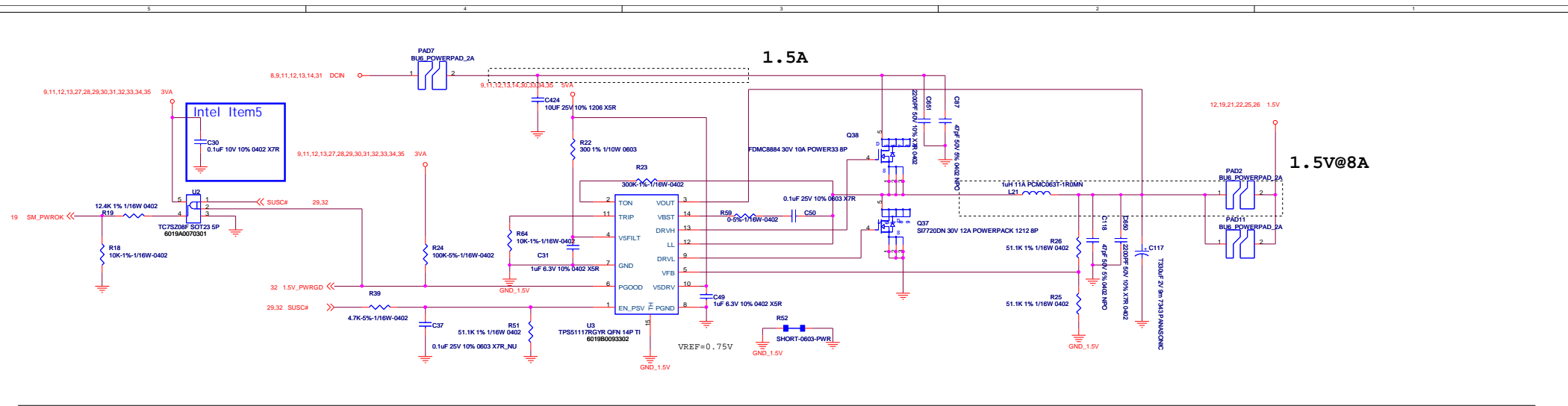


INVENTEC				
TITLE BAP31 (Penryn+ Cantiga+ICH9M)SFF				
Power Block Diagram				
SIZE C	CODE X01	DOC NUMBER D-CS-1310A264501-ALG	REV X01	
SHEET		1	7	of 36

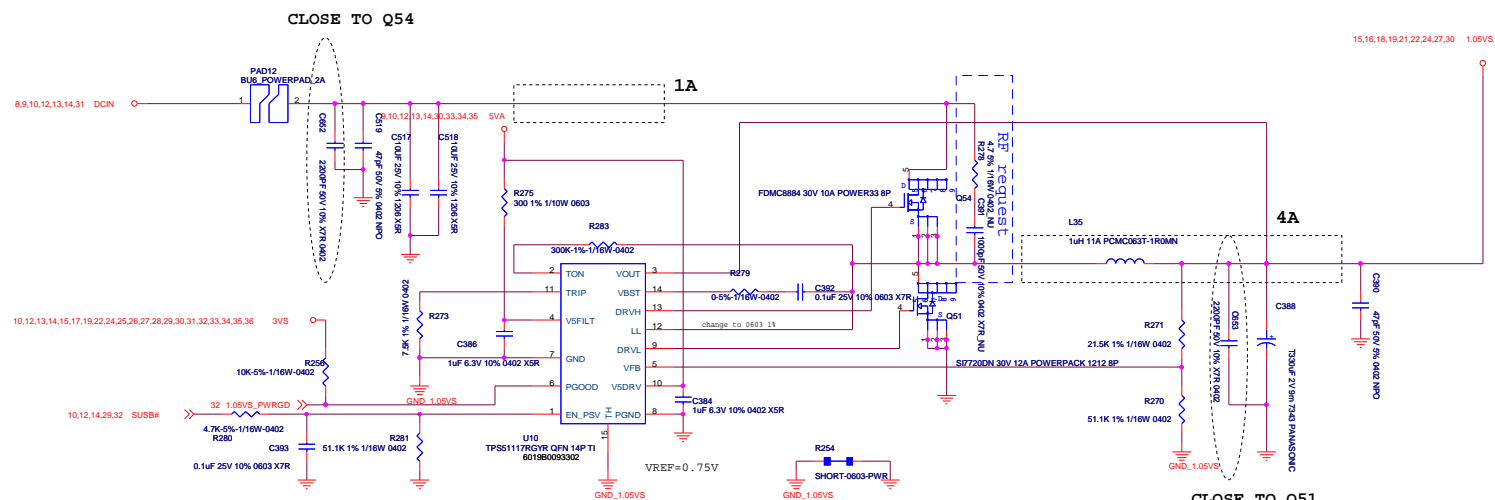
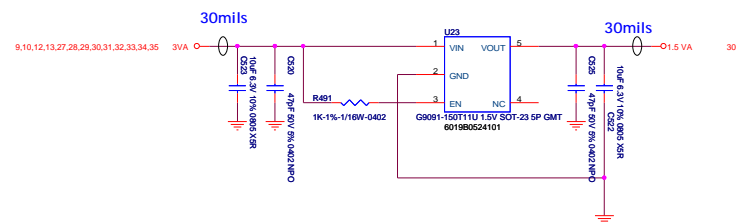
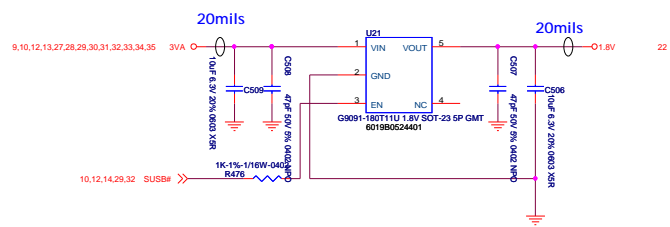






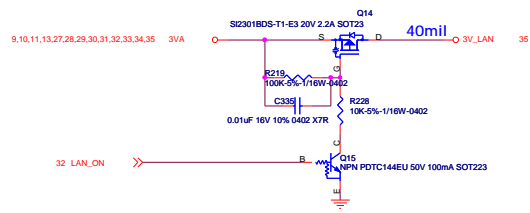
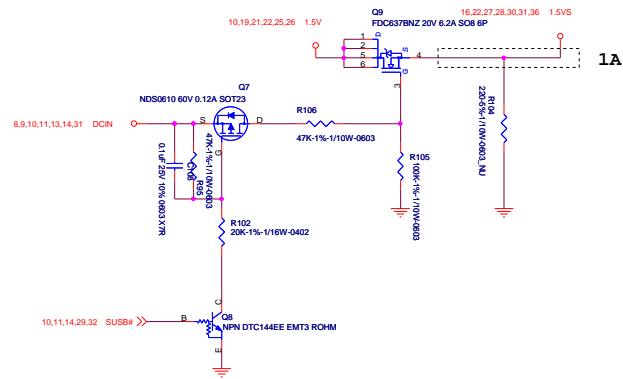


INVENTEC			
TITLE			
BAP31 (Penryn+Caniga+ICH9M)SF			
3VS/5VS/1.5V (DDR3)			
SIZE			
Custom	X01	DOC NUMBER	D-CS-1310A224501-ALG
SHEET			
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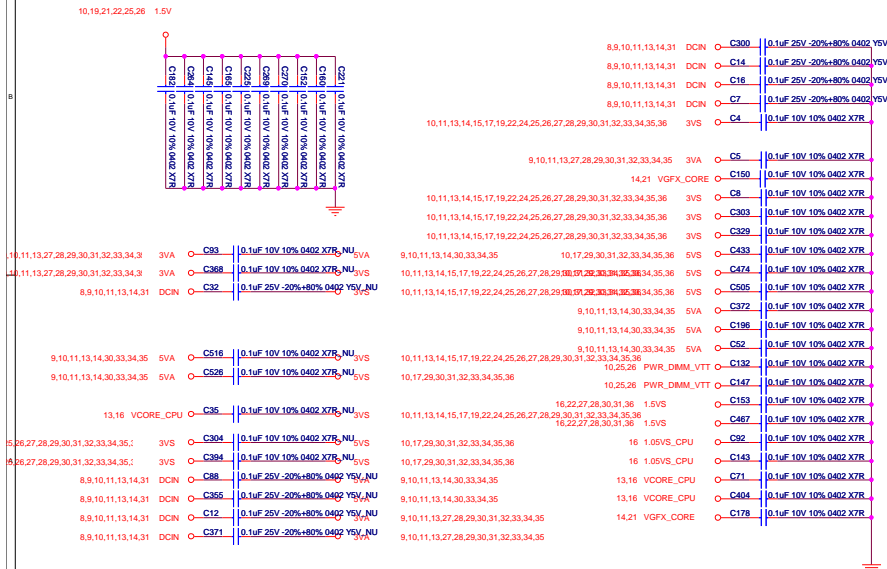


INVENTEC			
TITLE BAP31 (Penryn+Cantiga+ICH9M)SF			
1.05VS/1.5V/1.8V/1.5V			
SIZE	CODE	DOC NUMBER	REV
Custom	X01	D-CS-1310A2264501-ALG	X01
SHEET		11	of 36

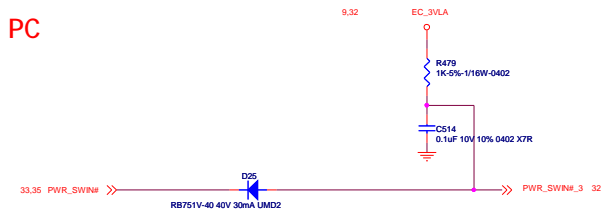
## 1.5VS



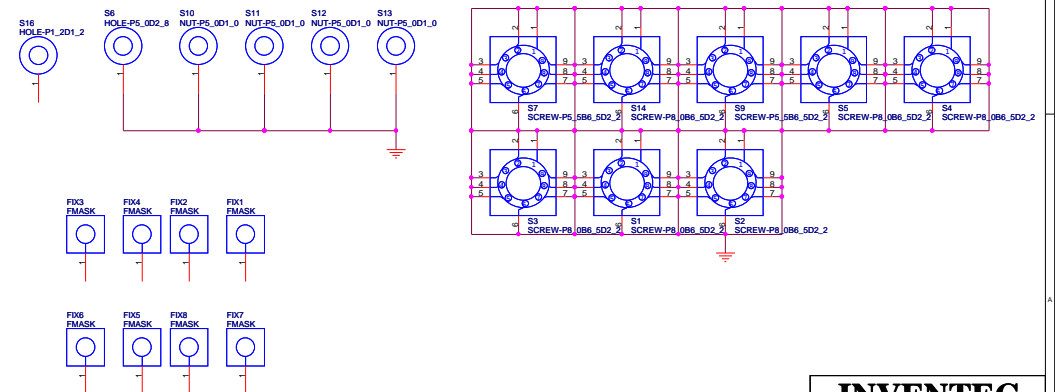
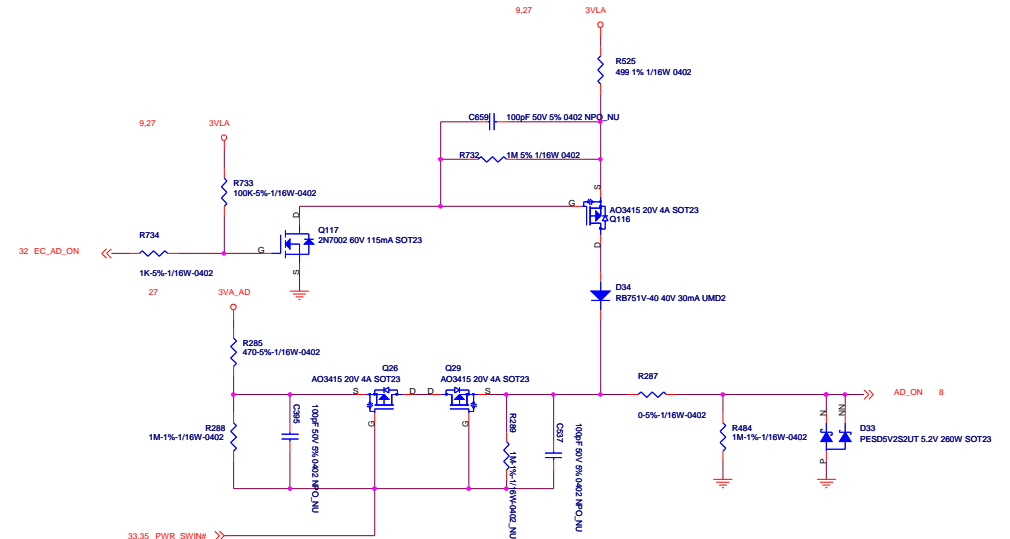
## EMI Cap



## For Green PC



## None Green PC ---- NU

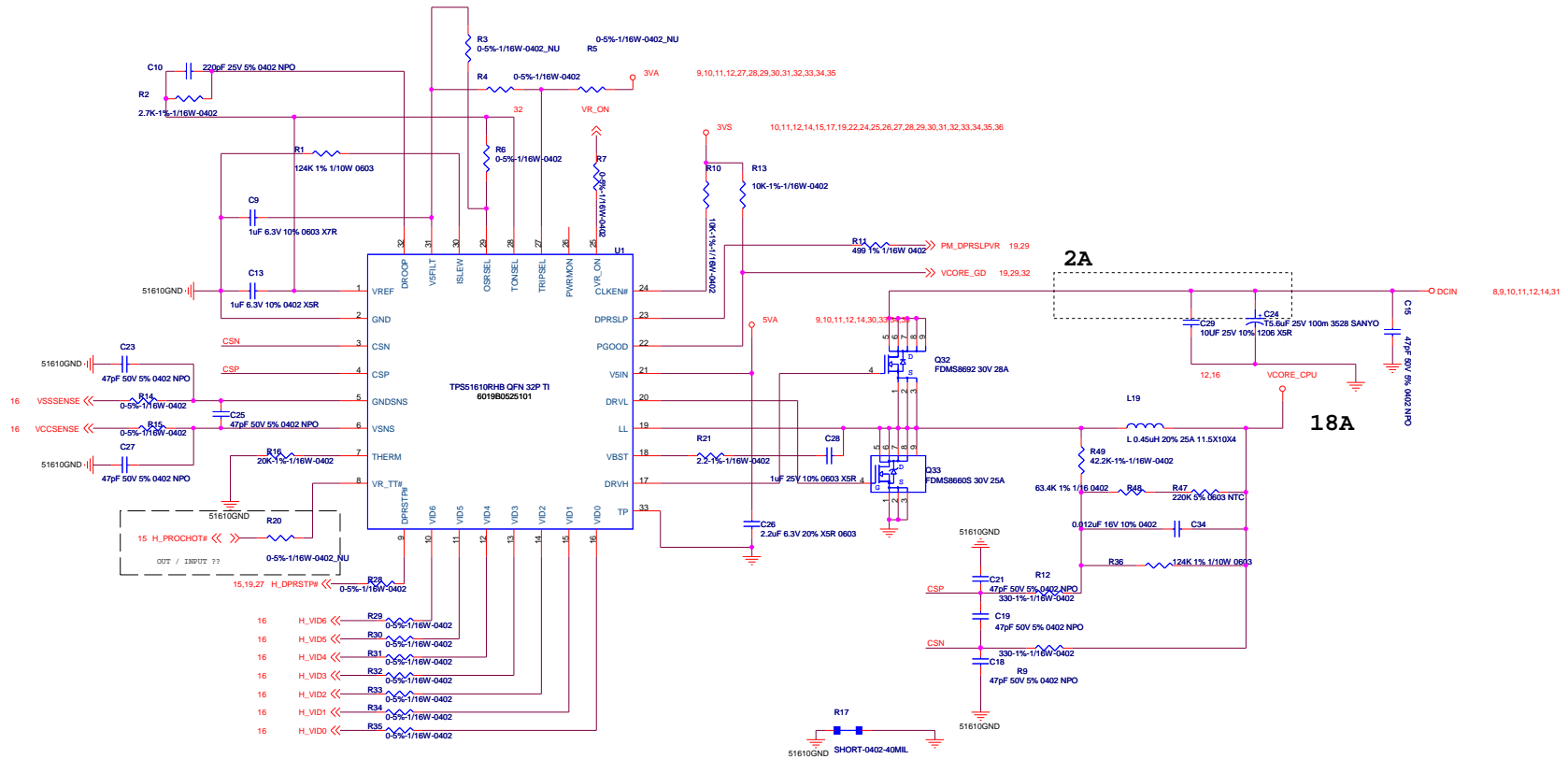


**INVENTEC**

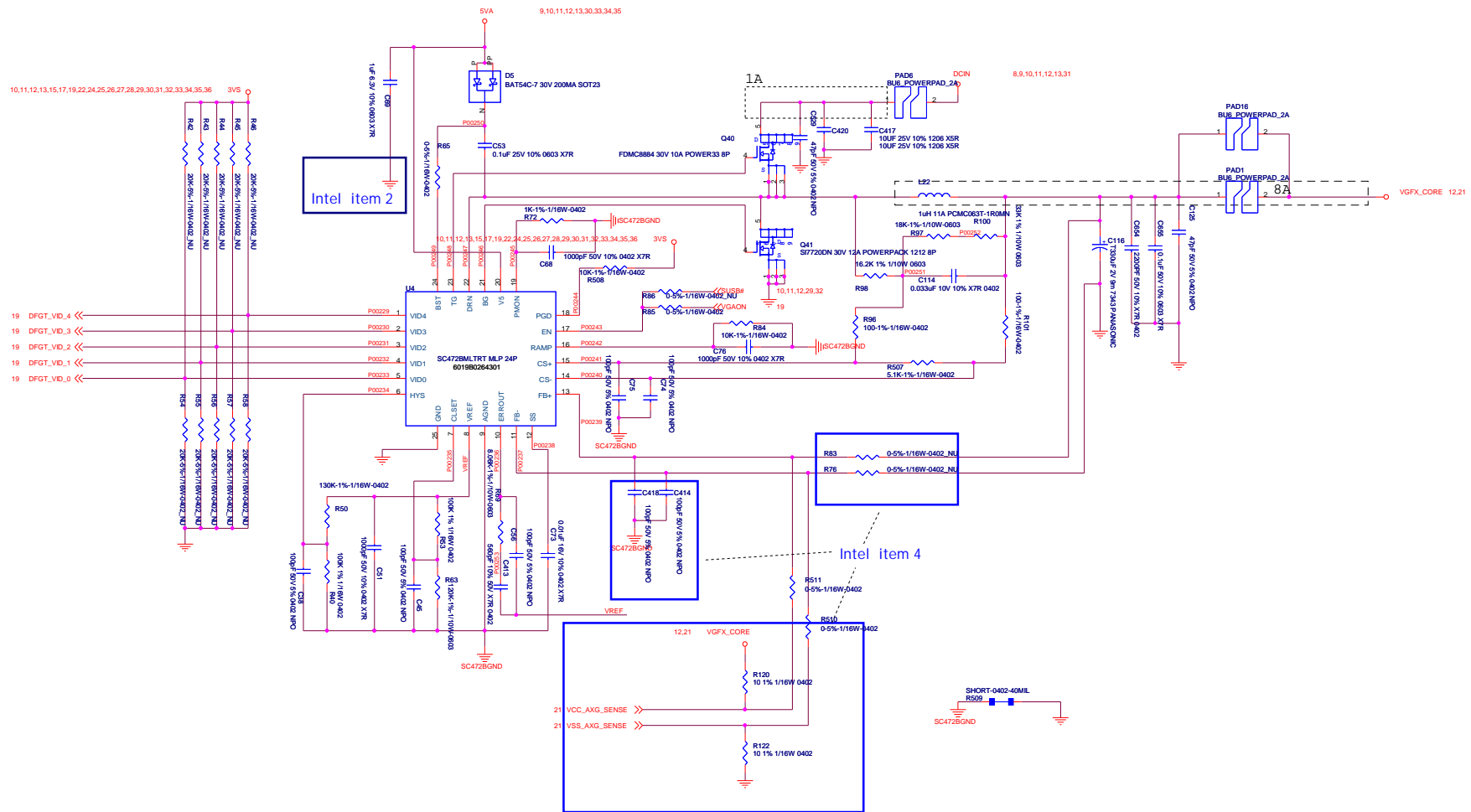
BAP31 (Penryn+Cantiga+ICH9M)SF  
Power on latch

CHANGE by: Miles Liu DATE: Tuesday, March 10, 2009

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INVENTEC				
TITLE BAP31 (Penryn+Cantiga+ICH9M)SFF				
CPU Core Power				
SIZE	CODE	DOC NUMBER	REV	
C	X01	D-CS-1310A2284501-ALG	X01	
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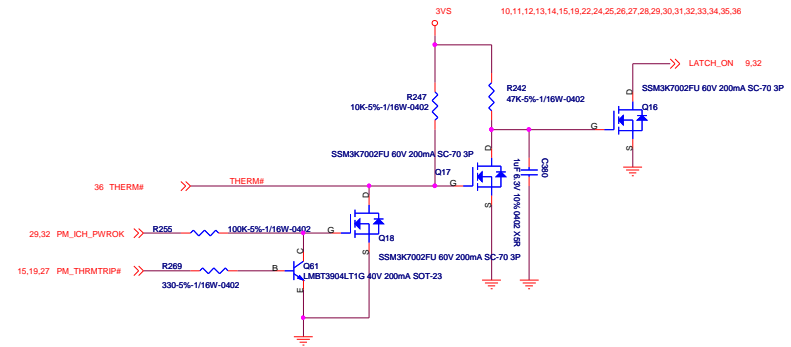
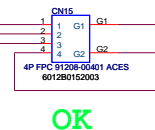


INVENTEC			
TITLE BAP31 (Penryn+Contiga+ICH9M)SF			
GPU CORE			
SIZE	CODE	DOC NUMBER	REV
Custom	X01	D-CS-1310A2264501-ALG	X01
SHEET		14	of 36



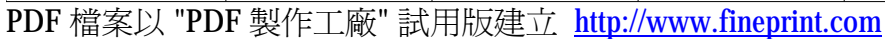


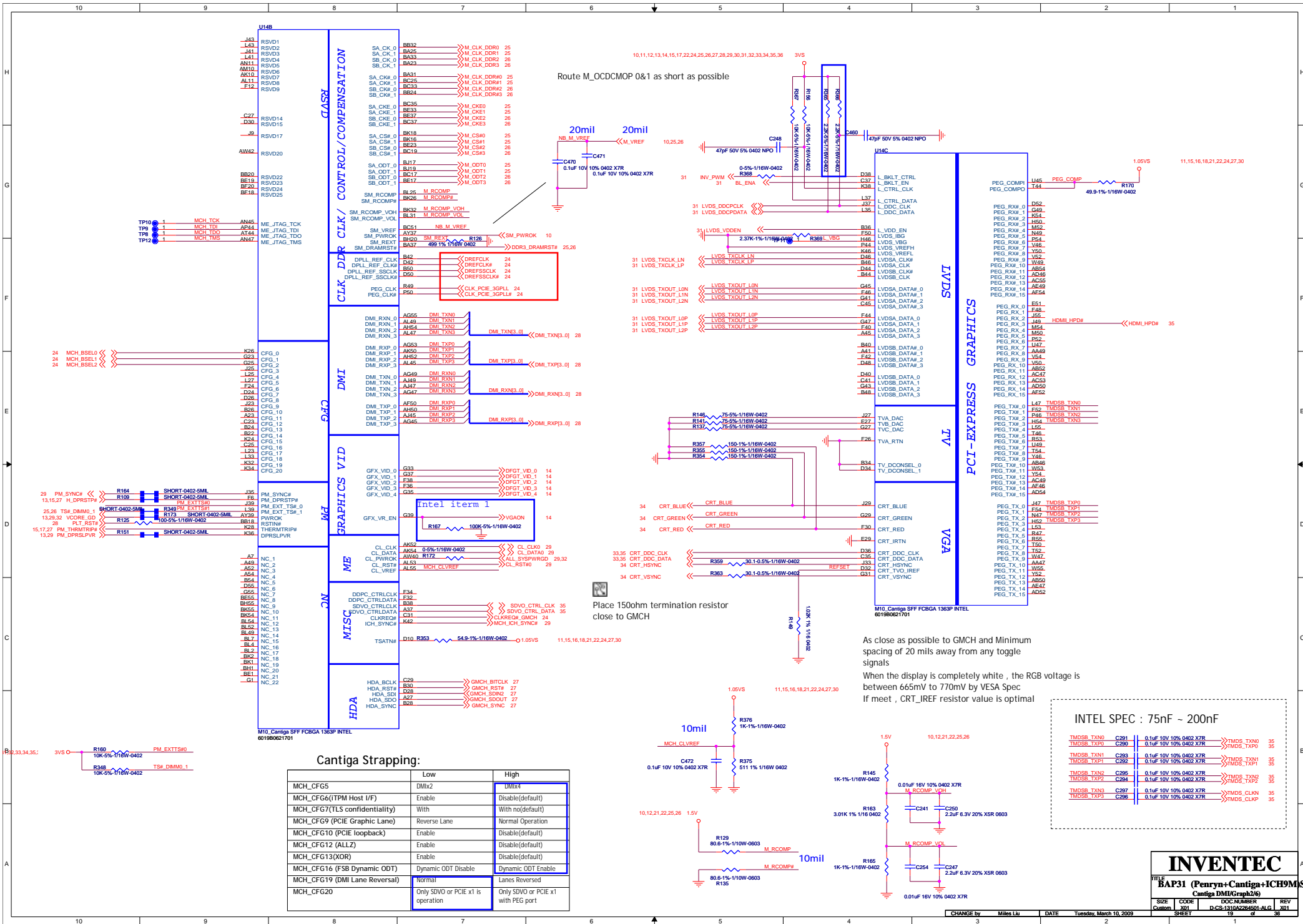


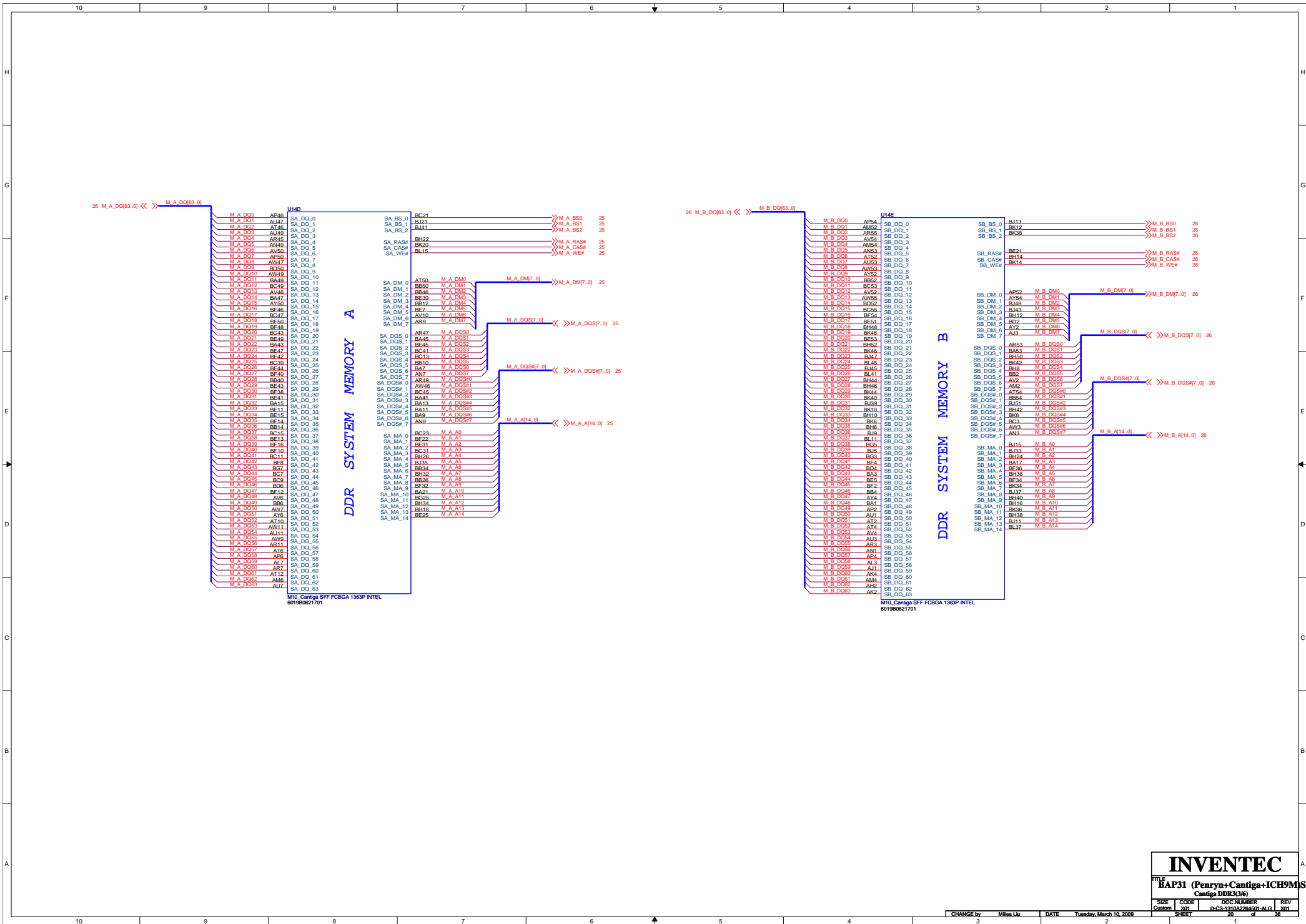
[illegible]

OK

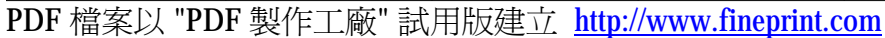
<b>INVENTEC</b>			
TITLE <b>BAP31 (Penryn+Centiga+ICH9M)SFF</b>			
CPU Thermal			
SIZE Custom	CODE X01	DOC NUMBER D-CS-1310A284501-ALG	REV X01
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<b>INVENTEC</b>			
TITLE BAP31 (Penryn+Cantiga+ICH9M)SFF Cantiga DDR3(36)			
SIZE	CODE	DOC NUMBER	REV
Custom	201	D-CS-1310A2264901-ALG	201
CHANGE by Miles Lu		DATE Tuesday, March 10, 2009	SHEET 20 of 36





Breakout/in LB/LV	Main Route LB/LV		Breakout/in LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Stripline
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Stripline
Stripline	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Stripline
Stripline	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Stripline	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Stripline
Stripline	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip

Parameter	Main Route Guideline	Breakout Guideline
Uncoupled Single End Impedance	55 +/- 15%	55 +/- 15%
Nominal Trace Width	Inner Layer : 4 mils Outer Layer : 5 mils	
Nominal Diddifferential Pair-Pitch	Inner Layer : 7 mils Outer Layer : 7 mils	Inner Layer : 4 mils Outer Layer : 5 mils
Pair-to-Pair Pitch	Inner Layer : 37 mils Outer Layer : 37 mils	Inner Layer : 27 mils Outer Layer : 27 mils
Bus-to-Bus Pitch	Inner Layer : 22 mils Outer Layer : 20 mils	Inner Layer : 15 mils Outer Layer : 12 mils
Reference Plane	Ground	Ground
Splits/Voids	No routing over plane splits No routing over voids	
Trace Length-LA (GMCH Breakout)	Max = 250 mils	
Trace Length-LB (GMCH Breakout to Via2)	Max = 3600 mils	
Trace Length-LC (Via2 to Via3)	Max = 5900 mils	
Trace Length-LD (Via3 to ICH7m Breakout)	Max = 3600 mils	
Trace Length-LE (ICH7m Breakout)	Max = 400 mils	
Trace Length-L1 (LA+LB+LC+LD+LE)	Max = 8000 mils	
Trace Length-LV (ICH7m Breakout)	Max = 400 mils	
Trace Length-LW (ICH7m Breakout to Via2)	Max = 3600 mils	
Trace Length-LX (Via2 to Via3)	Max = 5900 mils	
Trace Length-LY (Via3 to GMCH Breakout)	Max = 3600 mils	
Trace Length-LZ (GMCH Breakout)	Max = 400 mils	
Trace Length-L2 (LV+LW+LX+LY+LZ)	Max = 8000 mils	

X	O
	<p> <math>S = \text{Spacing}</math>  <math>S = \text{Trace Width}</math> </p>

Breakout/in LA/LZ	Main Route LB/LC/LY	Main Route LD/LW	Breakout/in LE/LV
Stripline	Microstrip	Same Routing layer as LE/LV	Microstrip

Parameter	Main Route Guideline	Breakout Guideline
Uncoupled Single End Impedance	55 +/- 15%	55 +/- 15%
Nominal Trace Width	Inner Layer : 4 mils Outer Layer : 5 mils	Inner Layer : 4 mils Outer Layer : 5 mils
Nominal Differential Trace Space	Inner Layer : 7 mils Outer Layer : 7 mils	Inner Layer : 4 mils Outer Layer : 5 mils
Pair-to-Pair Pitch	Inner Layer : 37 mils Outer Layer : 37 mils	Inner Layer : 27 mils Outer Layer : 27 mils
Bus-to-Bus Pitch	Inner Layer : 20 mils Outer Layer : 20 mils	Inner Layer : 15 mils Outer Layer : 12 mils
Reference Plane	Ground	Ground
Splits/Voids	No routing over plane splits No routing over voids	
Trace Length-LA (ICH7m Breakout)	Max = 400 mils	
Trace Length-LB (ICH7m Breakout to AC cap)	Max = 10750 mils	
Trace Length-LC (AC cap to PCIe CN)	Max = 10750 mils	
Trace Length-L1 (LA+LB+LC)	Max = 12000 mils	
Trace Length-LY (PCIe CN to ICH7m Breakout)	Max = 11950 mils	
Trace Length-LZ (ICH7m Breakout)	Max = 400 mils	
Trace Length-L2 (LY+LZ)	Max = 12000 mils	

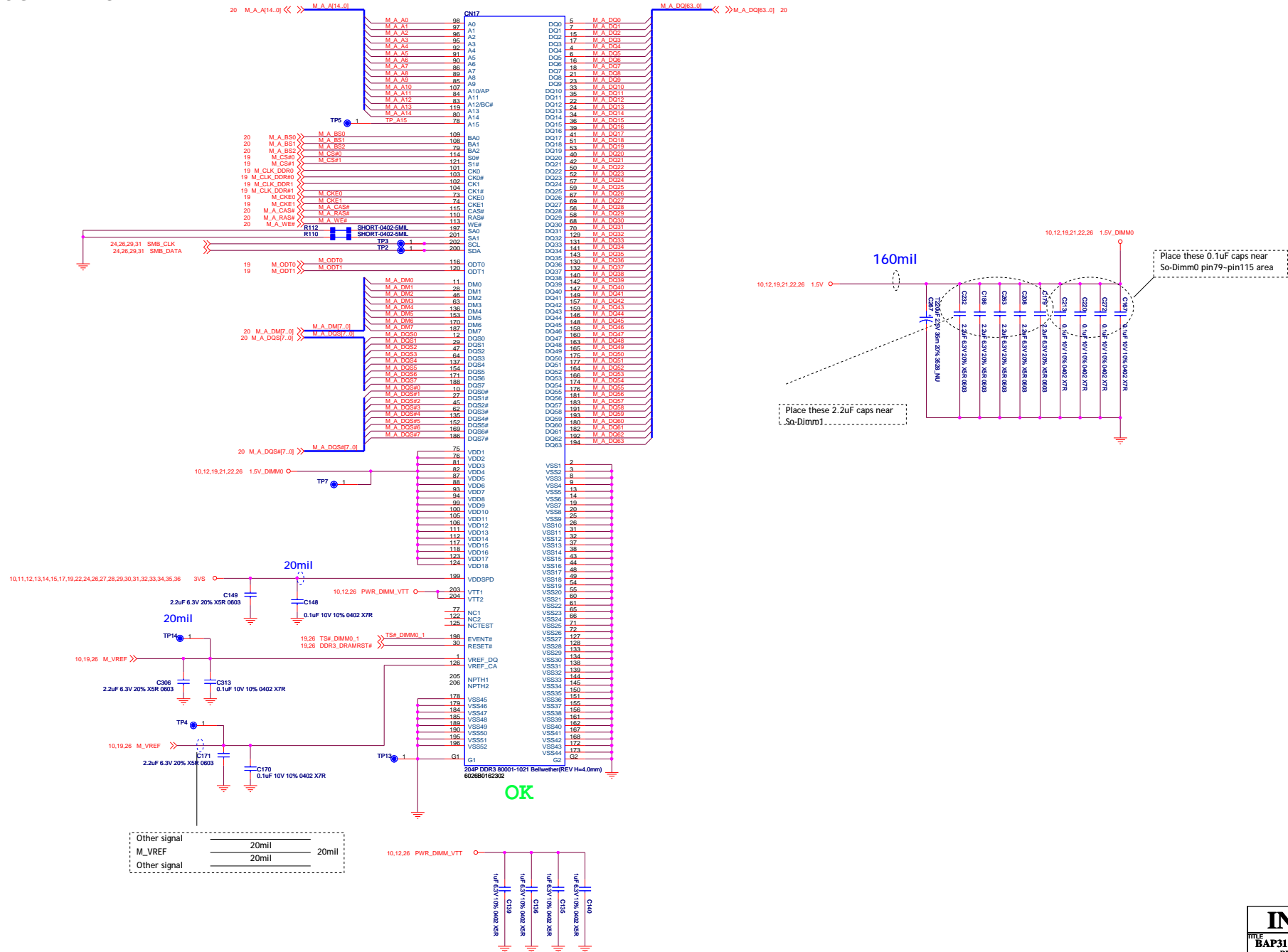
X	O
	<p> <math>S</math> = Spacing  <math>S</math> = Trace Width         </p>

SIZE Custom	CODE X01	DOC. NUMBER D-CS-1310A2264501-ALG	REV X01
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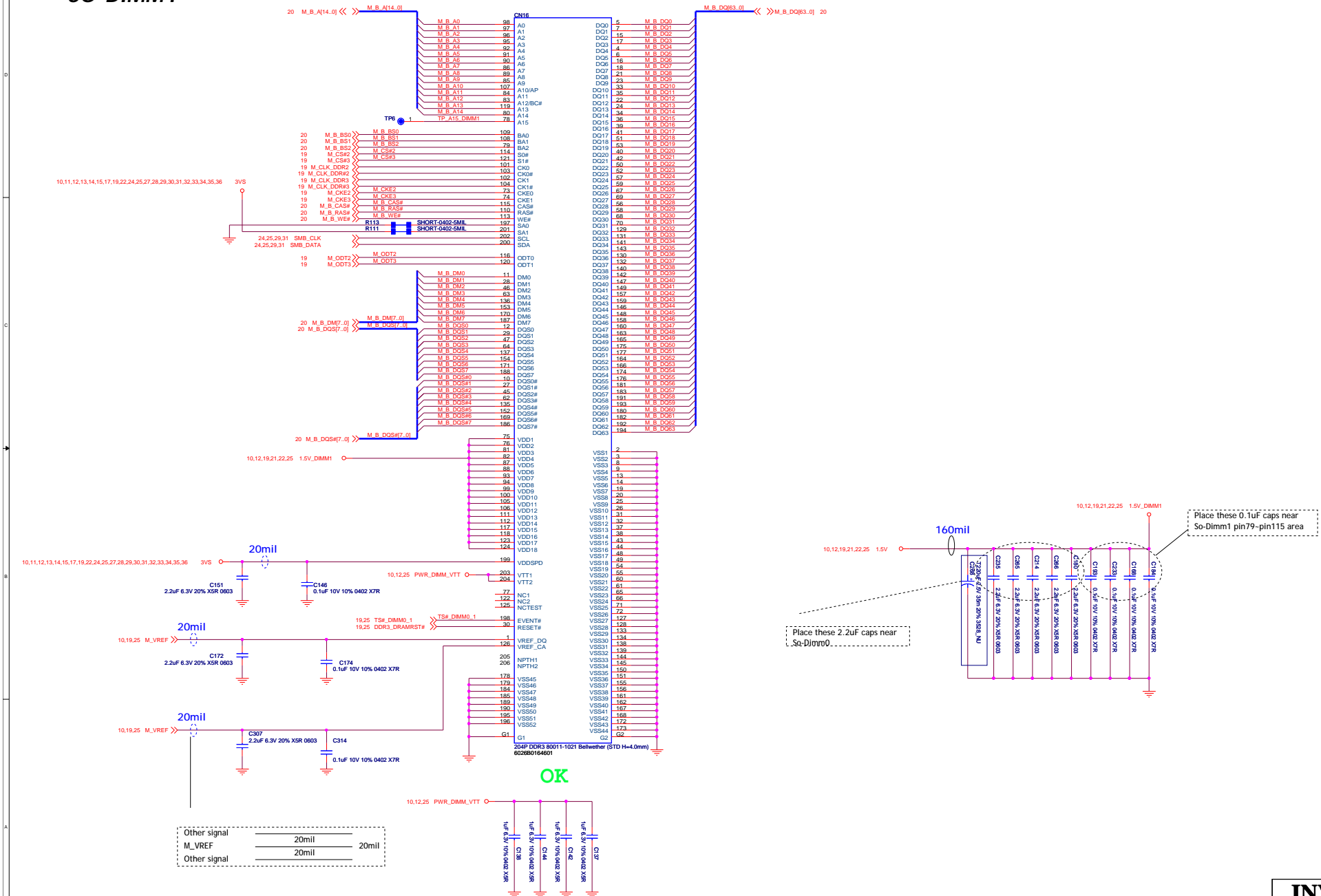


# SO-DIMMO



<b>INVENTEC</b>			
TITLE: BAP31 (Penryn+Camtiga+ICH9M)SFF			
DDR3 SDRAM SO-DIMMO			
SIZE: Custom	CODE: X01	DOC NUMBER: D-CS-1310A264501-ALG	REV: X01
CHANGE by: Milen Liu		DATE: Tuesday, March 10, 2009	SHEET: 26 of 36

# SO-DIMM1

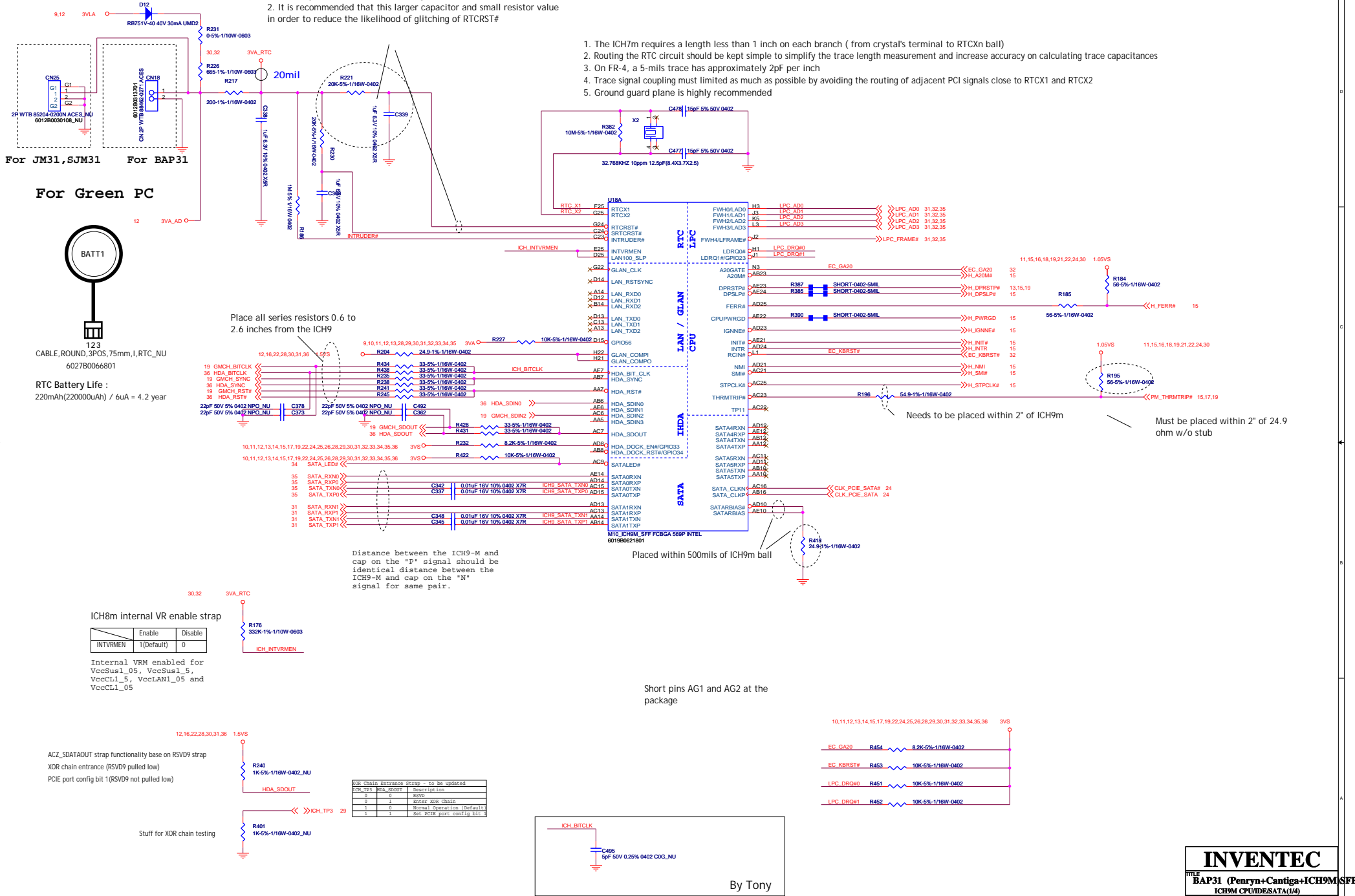


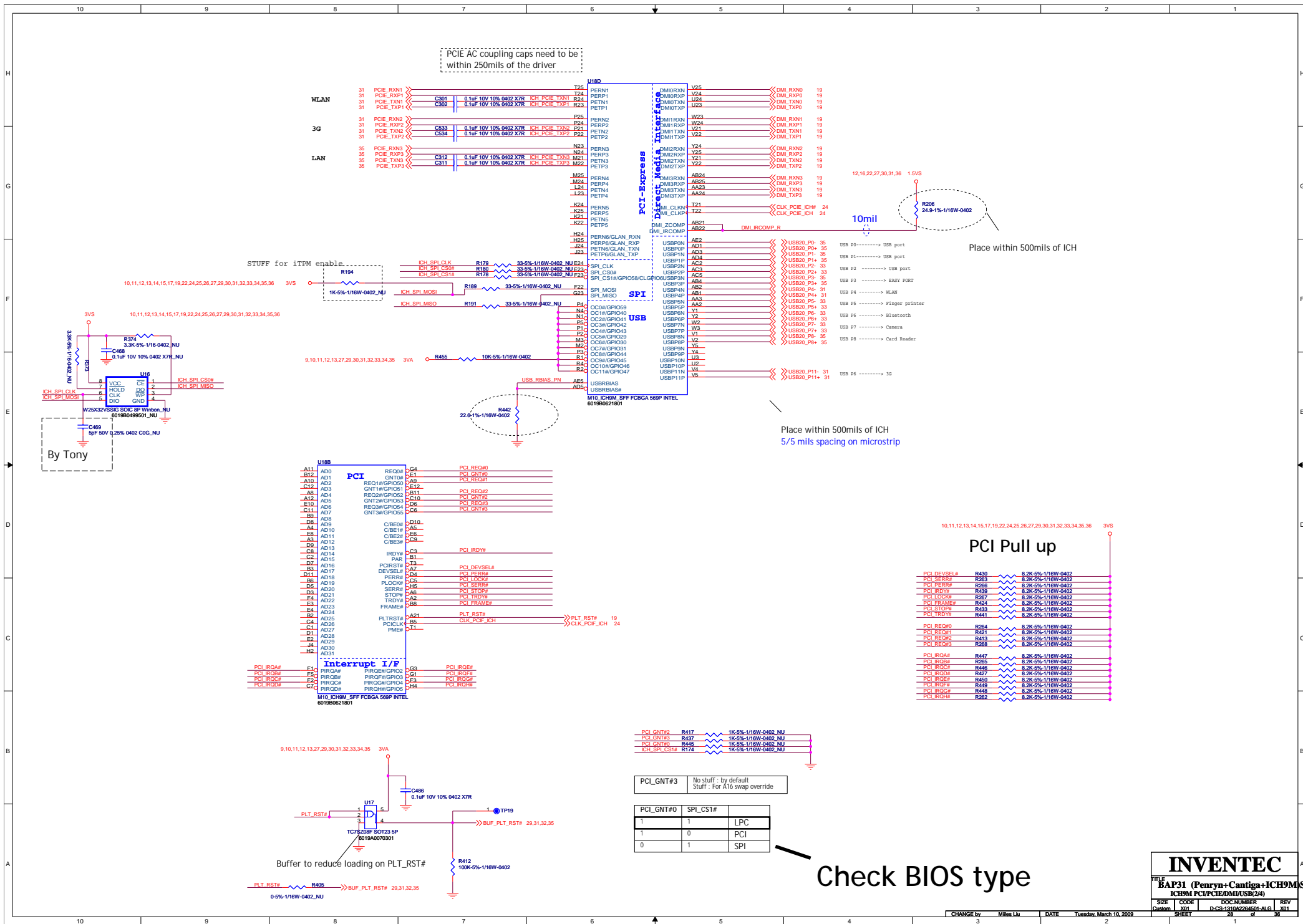
INVENTEC			
TITLE BAP31 (Penryn+Caniga+ICH9M)SFF			
DDR3 SDRAM SO-DIMM1			
SIZE	CODE	DOC NUMBER	REV
Custom	X01	D-CS-1310A284501-ALG	X01
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# RTC Circuit

1. RC delay time should be in the range of 18-25ms
2. It is recommended that this larger capacitor and small resistor value in order to reduce the likelihood of glitching of RTCRST#

1. The ICH7m requires a length less than 1 inch on each branch ( from crystal's terminal to RTCXn ball)
2. Routing the RTC circuit should be kept simple to simplify the trace length measurement and increase accuracy on calculating trace capacitances
3. On FR-4, a 5-mils trace has approximately 2pF per inch
4. Trace signal coupling must limited as much as possible by avoiding the routing of adjacent PCI signals close to RTCX1 and RTCX2
5. Ground guard plane is highly recommended

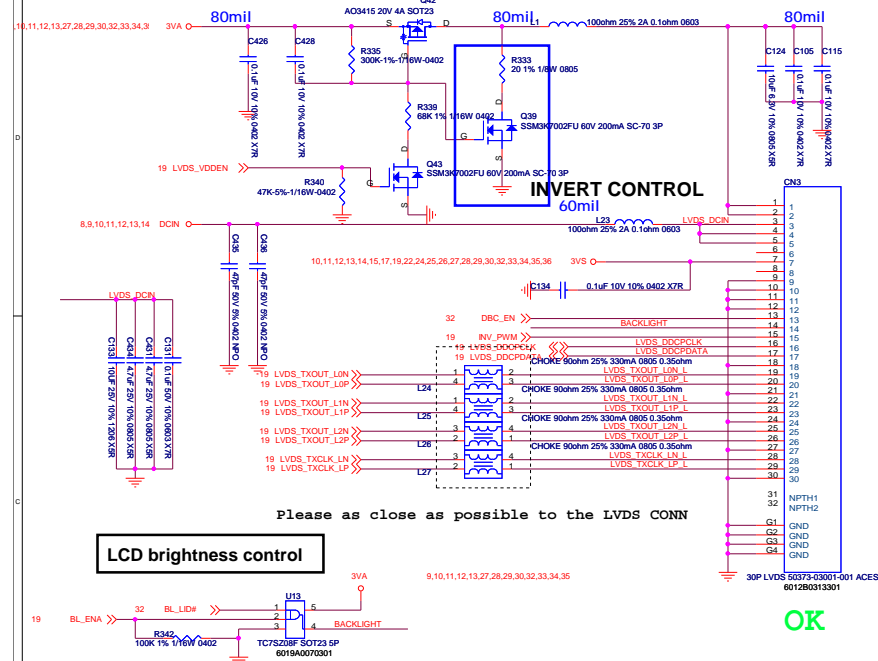




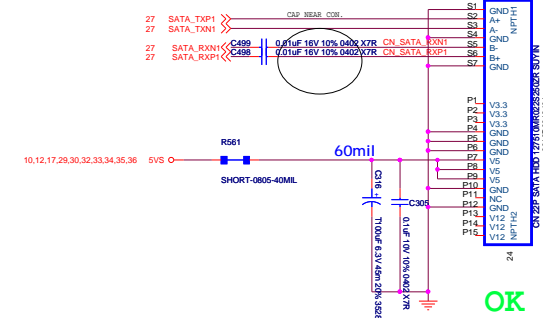




## LVDS Interface

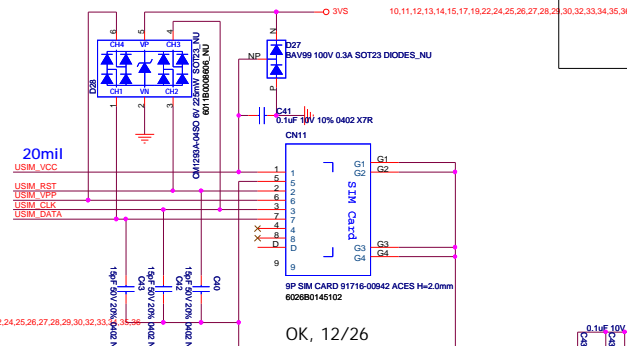


## HDD I/F

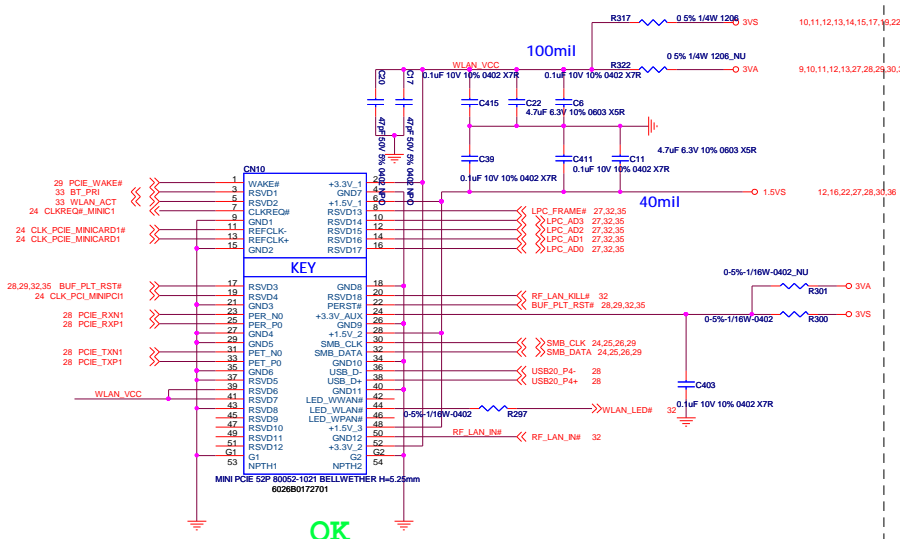


## SIM CARD slot

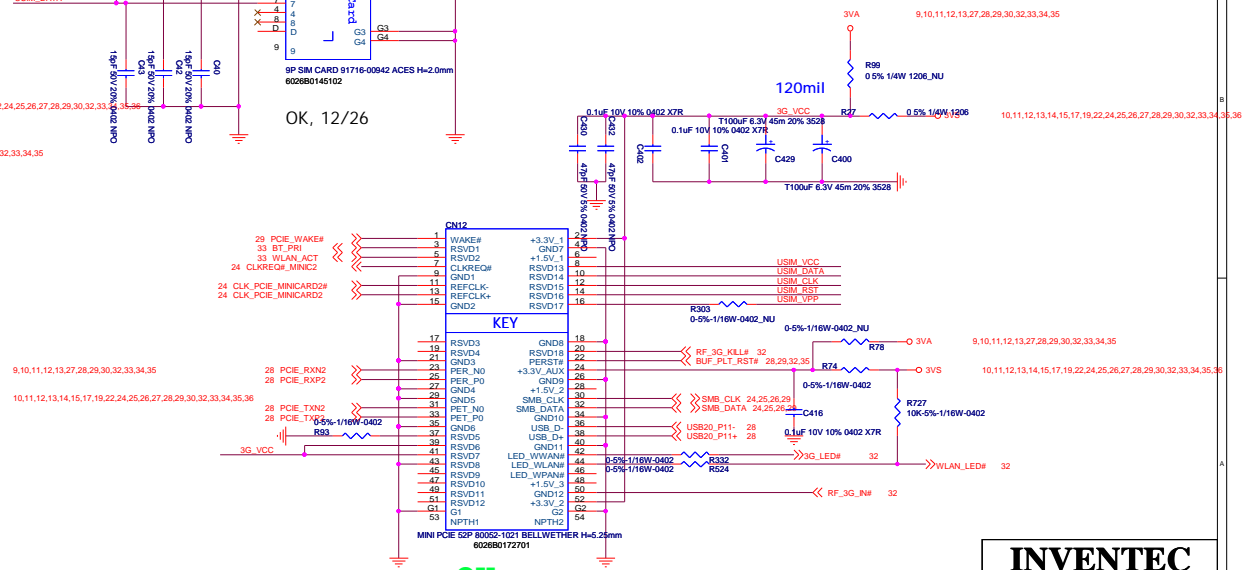
On Chip 5V to 3.3V regulator. No external regulator required  
On-Chip power MOSFETs for supplying flash media card power.



## PCIE Mini Card(WLAN)



## PCIE Mini Card for 3G

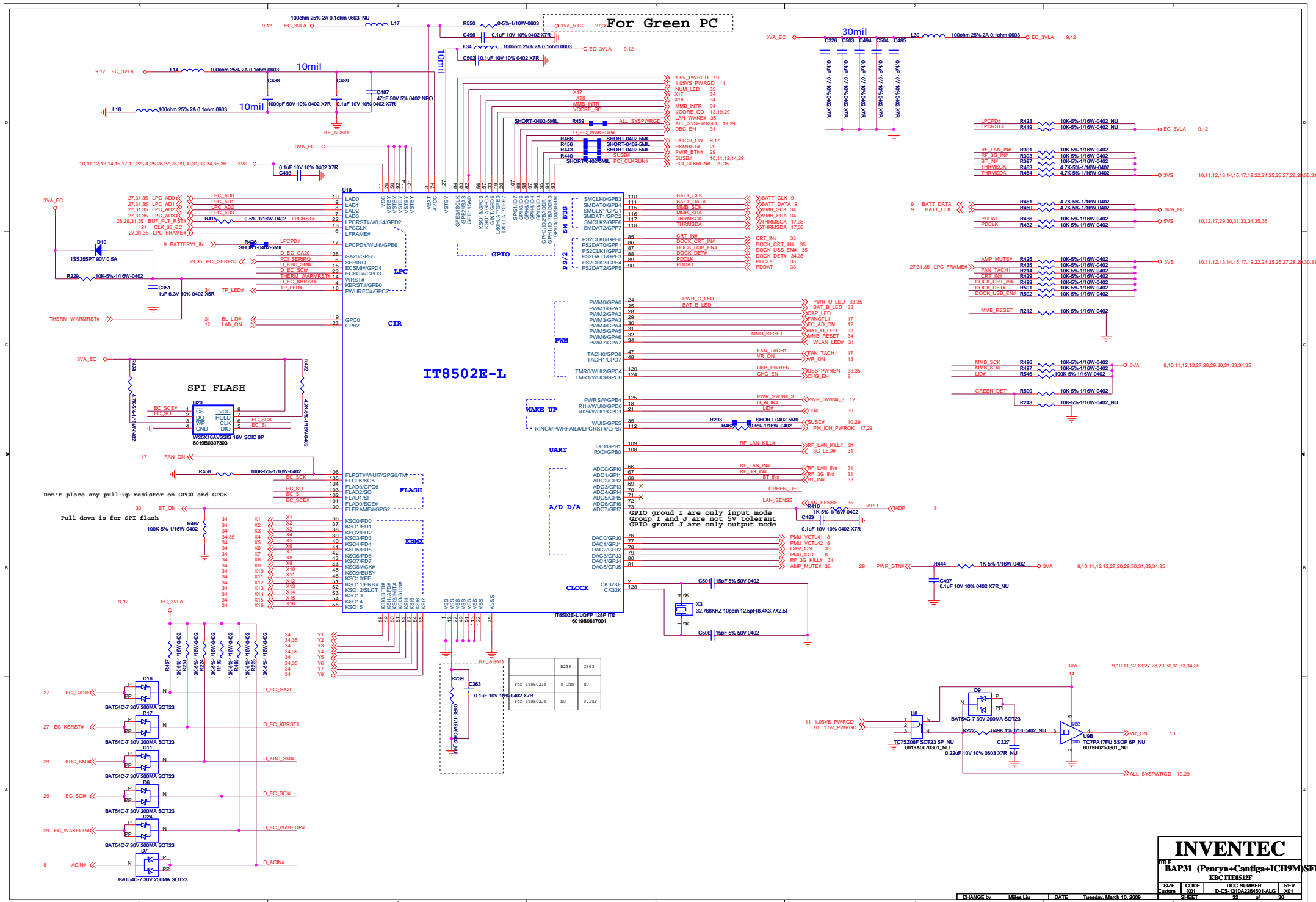


**INVENTEC**

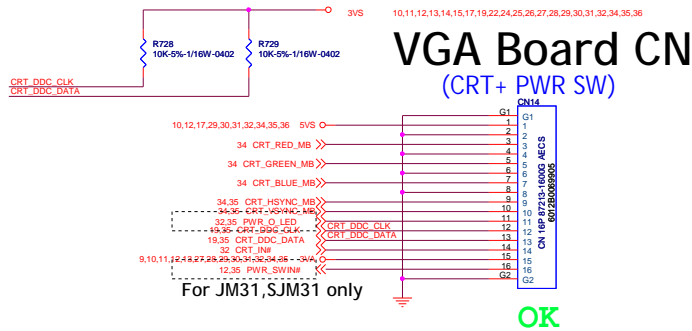
BAP31 (Penryn+Cntiga+ICH9M)SFF  
LCD CNN & WLAN & 3G

SIZE: Custom  
CODE: X01  
SHEET: 31 of 36

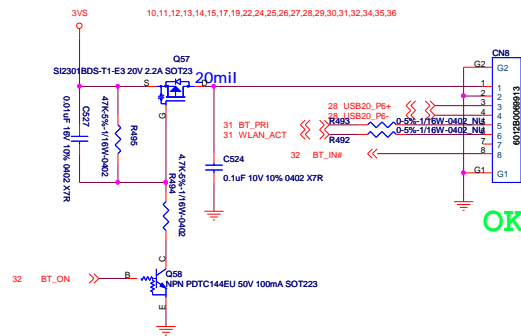




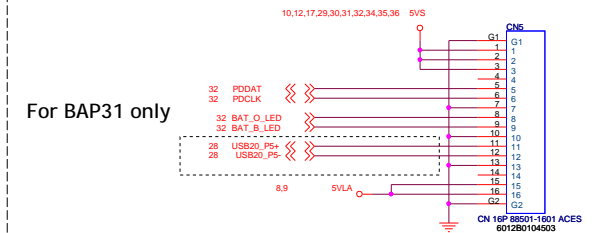




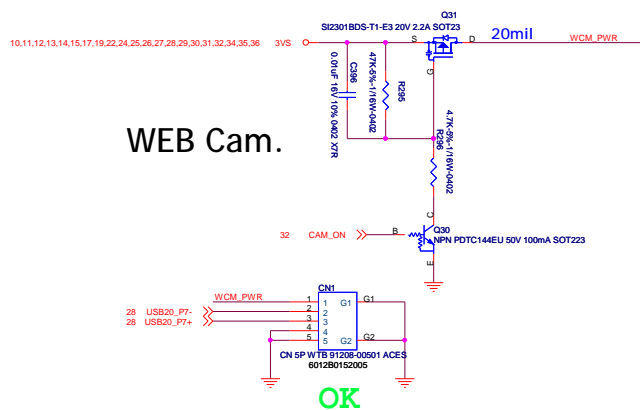
## Bluetooth CON.



## GLIDE PAD Board

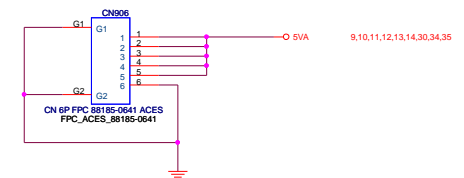
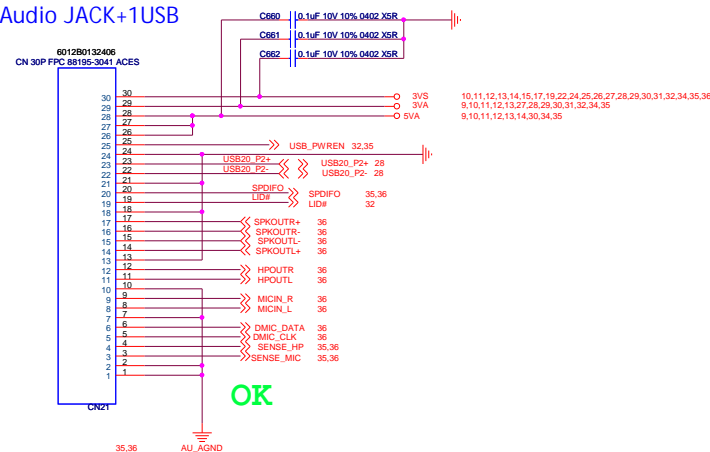


## WEB Cam.



## AUDIO Board CN

(Audio JACK+1USB)



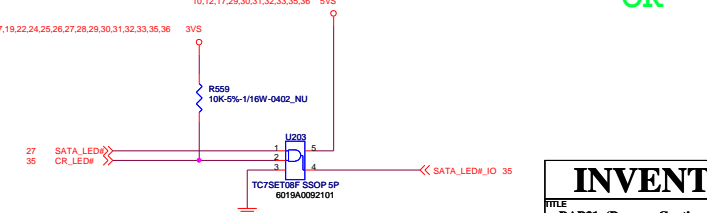
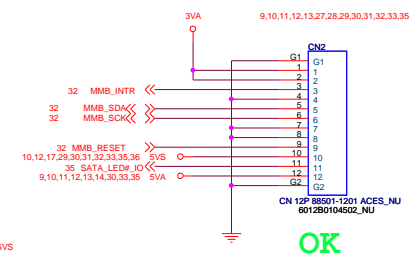
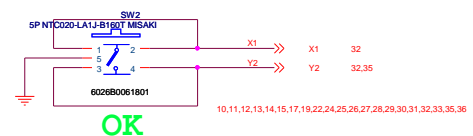
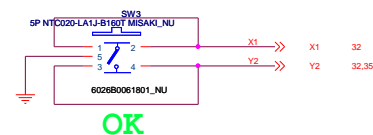
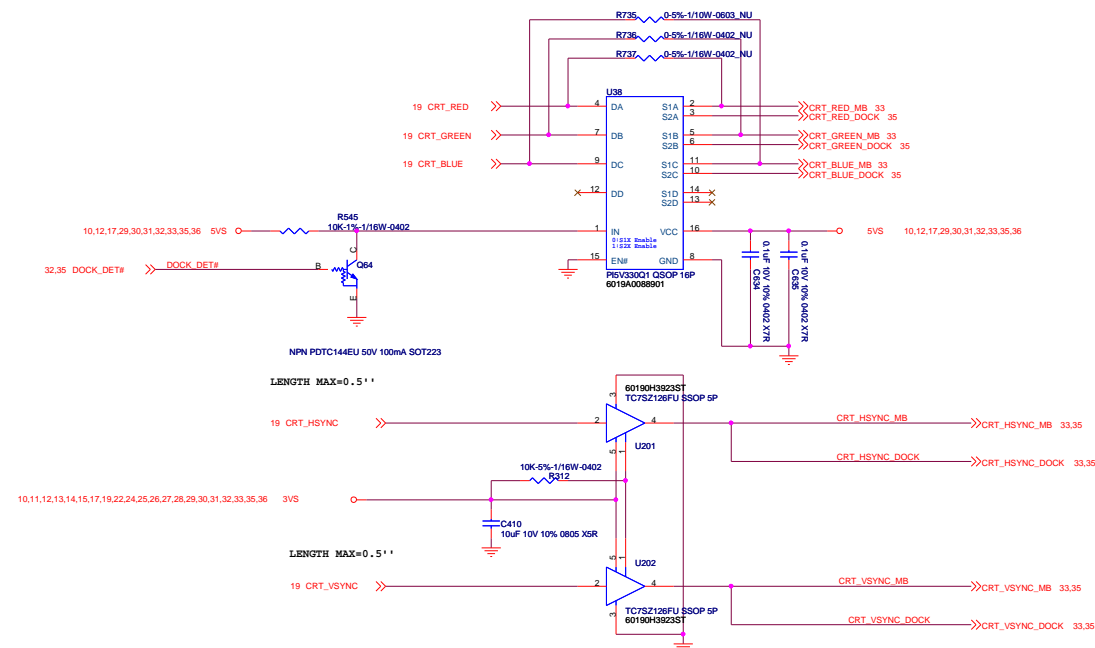
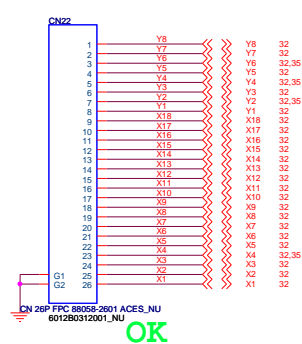
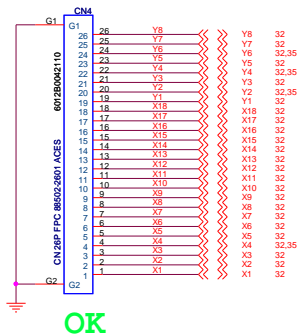
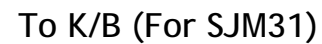
**INVENTEC**

**BAP31 (Penryn+Contiga+ICH9M) Daughter Connector**

SIZE	CODE	DOC NUMBER	REV
Custom	X01	D-CS-1310A2264501-ALG	X01

CHANGE by: Millen Liu DATE: Tuesday, March 10, 2009

SHEET 33 of 36



Pin 1 connection diagram for CN1 connector. The diagram shows a 12-pin connector with pins 1 through 12 labeled. Pin 1 is connected to G1. Pin 2 is connected to G1. Pin 3 is connected to G1. Pin 4 is connected to G1. Pin 5 is connected to G1. Pin 6 is connected to G1. Pin 7 is connected to G1. Pin 8 is connected to G1. Pin 9 is connected to G1. Pin 10 is connected to G1. Pin 11 is connected to G1. Pin 12 is connected to G1. A 5V regulator is connected to pin 12 and ground. A green 'OK' label is present.

BP BR501-0801 ACES  
601280104013

3V5 10,11,12,13,14,15,17,19,22,24,25,26,27,28,29,30,31,32,33,34,36

USB20\_PG- 28  
USB20\_PG+ 28  
CR\_LED# 34

OK

33.36 AU\_AGND

36 MICIN\_L\_DOCK

36 LIN\_L\_DOCK

36 LIN\_R\_DOCK

36 HPOUT\_L\_DOCK

36 HPOUT\_R\_DOCK

33.36 SPDFI\_DOCK

33.36 SENSE\_HP

33.36 SENSE\_MIC

36 LIN\_DOCKDET

20P FPC #B51-20A1 ACES  
690789018496

G2

G1

CN905

10

OK

22,24,25,26,27,28,29,30,31,32,33,34,36

The diagram illustrates the CN16 connector layout. On the left, SATA signals are connected to pins 1 through 7: SATA\_TXP0 (pin 1), SATA\_TXN0 (pin 2), SATA\_RXN0 (pin 3), SATA\_RXP0 (pin 4), and SATA\_RXP0 (pin 5). Pins 6 and 7 are also labeled SATA\_TXP0 and SATA\_TXN0. Power pads are connected to pins 8 and 9: BUS\_POWERPAD\_2K (pin 8) and BUS\_POWERPAD\_2A (pin 9). A capacitor C286 (0.01uF 10V 10% 0402 X7R) is connected between pins 10 and 11. The right side of the diagram shows the CN16 connector pins (G1 to G16) and their corresponding signals: G1 (SATA\_TXP0), G2 (SATA\_TXN0), G3 (SATA\_RXN0), G4 (SATA\_RXP0), G5 (SATA\_RXP0), G6 (SATA\_TXP0), G7 (SATA\_TXN0), G8 (SATA\_RXN0), G9 (SATA\_RXP0), G10 (SATA\_RXP0), G11 (SATA\_TXP0), G12 (SATA\_TXN0), G13 (SATA\_RXN0), G14 (SATA\_RXP0), G15 (SATA\_RXP0), and G16 (SATA\_TXP0). A green 'OK' label is located in the bottom right corner.

6012B0000511  
CN 12P WTB 86231-1200 ACES

Signal	Pin
34 CRT_RED_DOCK	12
34 CRT_GREEN_DOCK	11
34 CRT_BLUE_DOCK	10
33,34 CRT_VSYNC_DOCK	9
33,34 CRT_HSYNC_DOCK	8
19,33 CRT_DDC_DATA	7
19,33 CRT_DDC_CLK	6
32 DOK_CRT_RH	5
	4
	3
	2
	1

09504

[illegible][illegible][illegible]

TITLE			
<b>BAP31 (Penryn+Contiga+ICH9M)SFF BDP</b>			
SIZE	CODE	DOC. NUMBER	REV
Custom	X01	D-CS-1310A2264501-ALG	X01
SHEET		35	of 36

